

HMC344LP3

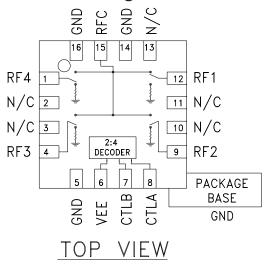
GaAs MMIC SP4T NON-REFLECTIVE SWITCH, DC - 8.0 GHz

Typical Applications

This switch is suitable for usage in DC - 8.0 GHz 50-Ohm or 75-Ohm systems:

- Broadband
- Fiber Optics
- Switched Filter Banks
- Wireless below 8 GHz

Functional Diagram



Features

Broadband Performance: DC - 8.0 GHz

High Isolation: 40 dB@ 6 GHz

Low Insertion Loss: 1.8 dB@ 6 GHz

Integrated 2:4 TTL Decoder

LP3 SMT Package

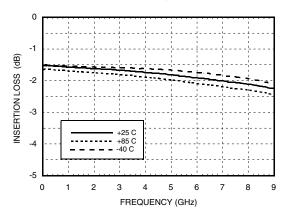
General Description

The HMC344LP3 is a broadband non-reflective GaAs MESFET SP4T switch in a low cost leadless surface mount package. Covering DC to 8 GHz, this switch offers high isolation and low insertion loss and extends the frequency coverage of Hittite's SP4T switch product line. This switch also includes an on board binary decoder circuit which reduces the required logic control lines to two. The switch operates using a negative control voltage of 0/-5V, and requires a fixed bias of -5V.

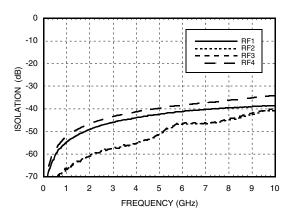
Electrical Specifications, $T_{\Delta} = +25^{\circ}$ C, With 0/-5V Control, 50 Ohm System

Parameter		Frequency	Min.	Тур.	Max.	Units
Insertion Loss		DC - 2.0 GHz DC - 6.0 GHz DC - 8.0 GHz		1.6 1.8 2.1	2.0 2.2 2.5	dB dB dB
Isolation		DC - 2.0 GHz DC - 4.0 GHz DC - 6.0 GHz DC - 8.0 GHz	43 36 34 31	48 41 40 36		dB dB dB dB
Return Loss	"On State"	DC - 2.0 GHz DC - 4.0 GHz DC - 6.0 GHz DC - 8.0 GHz	12 9 8 5	15 12 11 8		dB dB dB dB
Return Loss	"Off State"	DC - 8.0 GHz	7	10		dB
Input Power for 1 dB Compression		0.5 - 8.0 GHz	17	21		dBm
Input Third Order Intercept (Two-Tone Input Power = +7 dBm Each Tone)		0.5 - 8.0 GHz	37	40		dBm
Switching Characteristics tRISE, tFALL (10/90% RF) tON, tOFF (50% CTL to 10/90% RF)		DC - 8.0 GHz		35 150		ns ns

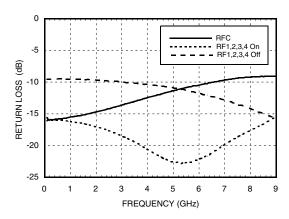
Insertion Loss vs. Temperature



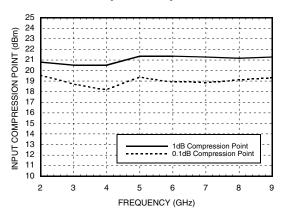
Isolation



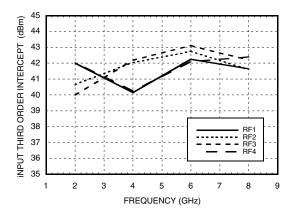
Return Loss



0.1 and 1 dB Input Compression Point



Input Third Order Intercept Point



^{*} Isolation is recorded above insertion loss & measured at output of switch.



Absolute Maximum Ratings

Bias Voltage Range (Vee)	-7.0 Vdc
Control Voltage Range (A & B)	Vee -0.5V to +1.0 Vdc
Channel Temperature	150 °C
Thermal Resistance (Insertion Loss Path)	143 °C/W
Thermal Resistance (Terminated Path)	1,030 °C/W
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C
Maximum Input Power	+24 dBm

Bias Voltage & Current

Vee Range = -5.0 Vdc ± 10%			
Vee lee (Typ.) (Vdc) (mA)		lee (Max.) (mA)	
-5.0	3.0	6.0	

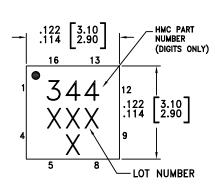
Truth Table

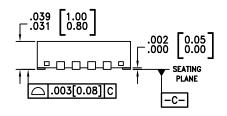
Control Input		Signal Path State	
А	В	RFCOM to:	
High	High	RF1	
Low	High	RF2	
High	Low	RF3	
Low	Low	RF4	

Control Voltages

State	Bias Condition	
Low	-3V to 0 Vdc @ 60 uA Typical	
High	-5 to -4.2 Vdc @ 5 uA Typical	

Outline Drawing





BOTTOM VIEW .012 [0.30] PIN 16 .008 [0.20] MIN .061 [1.56] .057 [1.44] .022 [0.56] .017 [0.44] .057 [1.95] .059 [1.50] .059 EXPOSED GROUND PADDLE MUST BE CONNECTED TO RF/DC GROUND SQUARE

NOTES:

- MATERIAL PACKAGE BODY: LOW STRESS INJECTION MOLDED PLASTIC SILICA AND SILICON IMPREGNATED.
- 2. LEAD AND GROUND PADDLE MATERIAL: COPPER ALLOY
- 3. LEAD AND GROUND PADDLE PLATING: Sn/Pb SOLDER
- 4. DIMENSIONS ARE IN INCHES [MILLIMETERS].
- 5. LEAD SPACING TOLERANCE IS NON-CUMULATIVE
- PAD BURR LENGTH SHALL BE 0.15mm MAXIMUM. PAD BURR HEIGHT SHALL BE 0.05mm MAXIMUM.
- 7. PACKAGE WARP SHALL NOT EXCEED 0.05mm.
- 8. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
- 9. REFER TO HITTITE APPLICATION NOTE FOR SUGGESTED PCB LAND PATTERN.

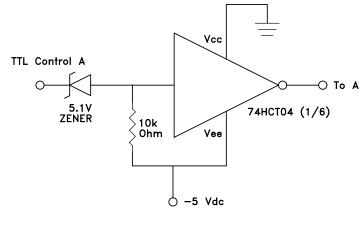


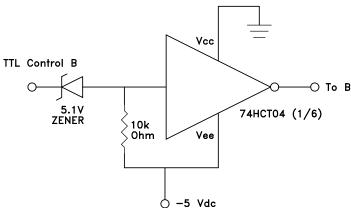
Pin Descriptions

Pin Number	Function	Description	Interface Schematic
1, 4, 9, 12, 15	RF4, RF3, RF2, RF1, RFC	This pin is DC coupled and matched to 50 Ohm. Blocking capacitors are required if RF line potential is not equal to 0V.	
2, 3, 10, 11, 13	N/C	This pin should be connected to PCB RF ground to maximize isolation.	
5, 14, 16	GND	Package bottom has exposed metal paddle that must also be connected to PCB RF ground.	
6	VEE	Supply Voltage -5V ± 10%	о 5pF 2к
7	CTLB	See truth table and control voltage table.	100K
8	CTLA	See truth table and control voltage table.	Vee



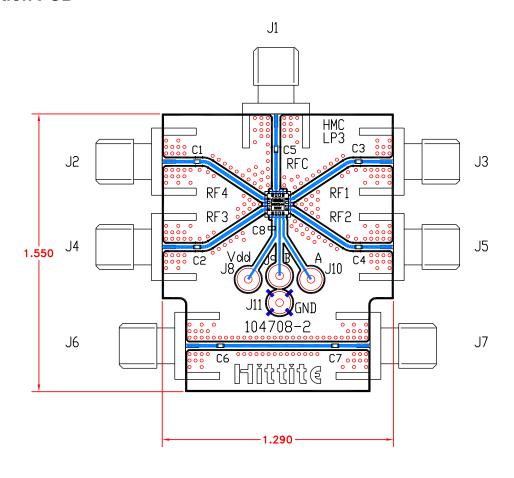
TTL Interface Circuit







Evaluation PCB



List of Material

Item	Description	
J1 - J7	PC Mount SMA RF Connector	
J8 - J11	DC Pin	
C1 - C7	100 pF Capacitor, 0402 Pkg.	
C8	10k pF Capacitor, 0603 Pkg.	
U1	HMC344LP3 SP4T Switch	
PCB*	104708 Evaluation PCB 1.29"x1.55"	
* Circuit Board Material: Rogers 4350		

The circuit board used in the final application should be generated with proper RF circuit design techniques. Signal lines at the RF port should have 50 ohm impedance and the package ground leads and backside ground slug should be connected directly to the ground plane similar to that shown above. The evaluation circuit board shown above is available from Hittite Microwave Corporation upon request.